



#### N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Features**

- Low On-Resistance
  - 38 mΩ @ V<sub>GS</sub> = 10V
  - 64 m $\Omega$  @ V<sub>GS</sub> = 4.5V
- Low Input Capacitance
- Fast Switching Speed
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

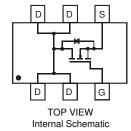
#### **Mechanical Data**

- Case: SOT-26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.015 grams (approximate)

SOT-26



TOP VIEW



Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Drain-Source Voltage	VDSS	30	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Drain Current (Note 1)	ID	4.0	Α
Pulsed Drain Current (Note 1)	IDM	16	А

### **Thermal Characteristics**

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 1)	PD	900	mW
Thermal Resistance, Junction to Ambient	R <sub>0JA</sub>	139	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-55 to +150	°C

1. Device mounted on FR-4 PCB, minimum recommended pad layout on 2oz. Copper pads.

2. No purposefully added lead.

Notes:

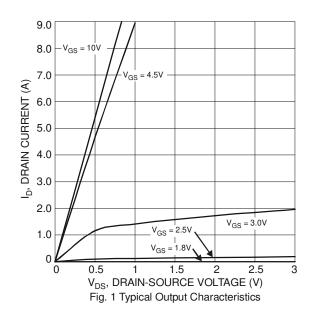
3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

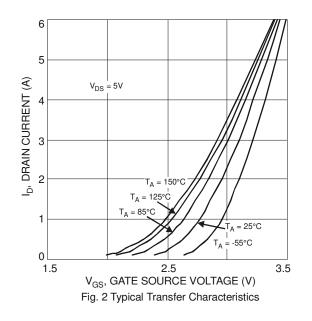


### Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)			_	_		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30		_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	800	nA	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_		±80 ±800	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$ $V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 4)	- I I		•			<u> </u>
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.2		2.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance		_	28	38	mΩ	$V_{GS} = 10V, I_D = 6A$
	R <sub>DS (ON)</sub>		50	64	1115.2	$V_{GS} = 4.5V, I_D = 5A$
Forward Transfer Admittance	Y <sub>fs</sub>	_	5.2	_	S	$V_{DS} = 5V, I_D = 3.1A$
Diode Forward Voltage (Note 4)	V <sub>SD</sub>	_	0.78	1.16	V	$V_{GS} = 0V, I_S = 2A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	Ciss	_	424	—	pF	
Output Capacitance	C <sub>oss</sub>	_	115	_	pF	$V_{DS} = 5V, V_{GS} = 0V, f = 1.0MHz$
Reverse Transfer Capacitance	C <sub>rss</sub>	_	81	_	pF	
Gate Resistance	R <sub>G</sub>	_	1.3	_	Ω	$V_{GS} = 0V V_{DS} = 0V, f = 1MHz$
SWITCHING CHARACTERISTICS						
Total Gate Charge	Qg	_	4.3 8.6	_		
Gate-Source Charge	Q <sub>gs</sub>	_	1.2	_	nC	$V_{DS} = 10V, V_{GS} = 10V, I_D = 10A$
Gate-Drain Charge	Q <sub>gd</sub>		2.5	_		$V_{DS} = 10V, V_{GS} = 10V, I_D = 10A$

Notes: 4. Short duration pulse test used to minimize self-heating effect.



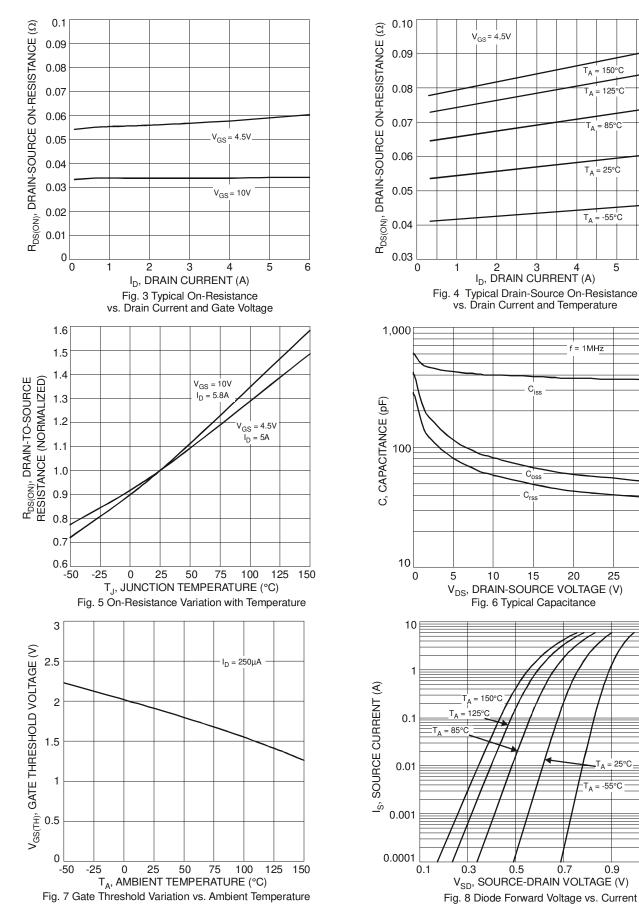




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6

30



1.1

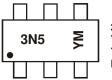


## Ordering Information (Note 5)

Part Number	Case	Packaging
DMN3051LDM-7	SOT-26	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**

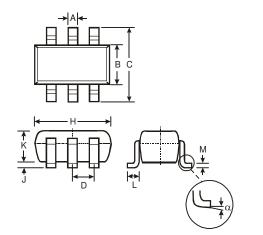


3N5 = Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key

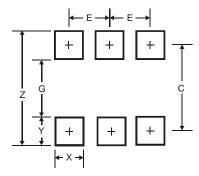
Year	2008		2009	2010		2011	2012		2013	2014		2015
Code	V		W	Х		Y	Z		А	В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	J Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

# **Package Outline Dimensions**



SOT-26						
Dim	Min	Max	Тур			
Α	0.35	0.50	0.38			
В	1.50	1.70	1.60			
С	2.70	3.00	2.80			
D	_	_	0.95			
Н	2.90	3.10	3.00			
J	0.013	0.10	0.05			
Κ	1.00	1.30	1.10			
L	0.35	0.55	0.40			
М	0.10	0.20	0.15			
α	0°	8°	_			
Ali D	All Dimensions in mm					

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
С	2.40
E	0.95



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